

Technical Data Sheet

Schulamid 66 GF35 H4 I1 BLK968001



Polyamide 66

Product Description

35% glass fiber reinforced PA 66, heat stabilized, electrically neutral and free of DPPD.

Processing Method Injection Molding

Attribute Heat Stabilized

Filler/Reinforcement Glass Fiber, 35%

Typical Properties	Nominal Value	Units	Test Method
Physical			
Density, (Method A)	1.40	g/cm ³	ISO 1183
Viscosity Number	145	cm ³ /g	ISO 307
Mechanical			
Tensile Strain at Break			
(Type 1A, 5 mm/min)	2.5	%	ISO 527-2
(Type 1A, 5 mm/min) - Conditioned	5.0	%	ISO 527-2
Tensile Stress at Break			
(Type 1A, 5 mm/min)	190	MPa	ISO 527-2
(Type 1A, 5 mm/min) - Conditioned	140	MPa	ISO 527-2
Tensile Modulus			
(1 mm/min, Type 1A)	11000	MPa	ISO 527-1
(1 mm/min, Type 1A) - Conditioned	8000	MPa	ISO 527-1
Impact			
Charpy Impact Strength - Notched			
(23 °C, Type 1, Edgewise, Notch A)	13	kJ/m ²	ISO 179
(-30 °C, Type 1, Edgewise, Notch A)	12	kJ/m ²	ISO 179
(23 °C, Type 1, Edgewise, Notch A) - Conditioned	20	kJ/m ²	ISO 179
(-30 °C, Type 1, Edgewise, Notch A) - Conditioned	12	kJ/m ²	ISO 179
Charpy Impact Strength - Unnotched			
(23 °C, Type 1, Edgewise)	90	kJ/m ²	ISO 179
(-30 °C, Type 1, Edgewise)	75	kJ/m ²	ISO 179
(23 °C, Type 1, Edgewise) - Conditioned	95	kJ/m ²	ISO 179
(-30 °C, Type 1, Edgewise) - Conditioned	85	kJ/m ²	ISO 179
Hardness			
Ball Indentation Hardness, (H 358/30)	250	MPa	ISO 2039-1
Thermal			

Deflection Temperature Under Load Unannealed (0.45 MPa), (Flatwise)	250	°C	ISO 75-2/B
Deflection Temperature Under Load Unannealed (1.80 MPa), (Flatwise)	250	°C	ISO 75-2/A
Electrical			
Volume Resistivity	>1.0E+13	ohm*m	IEC 62631-3-1
- Conditioned	10000000000	ohm*m	IEC 62631-3-1
Comparative Tracking Index (CTI)	450	V	IEC 60112
Surface Resistivity	>1.0E+15	ohm	IEC 60093
Flammable			
Burning Rate			
(2.00 mm)	30	mm/min	ISO 3795
(2.00 mm)	30	mm/min	FMVSS 302
Glow Wire Flammability Index	600	°C	IEC 60695-2-12

Injection Parameters	Nominal Value	Units
Drying Time	3.0 to 4.0	hr
Drying Temperature	80	°C
Suggested Max Moisture	0.040 to 0.10	%
Processing (Melt) Temp	280 to 300	°C
Mold Temperature	60 to 120	°C